

RESUME of Dr. Dyi-Chung Hu

Dr. **Dyi-Chung Hu** earned Ph. D. degree from MIT in Material Science and Engineering Department in 1984.

Later he joined IBM East Fishkill to develop thin film MCM substrate for high performance computer. In 1990, he went back to Taiwan and become Professor in National Chao Tung University. Later, he joined Industry Research Organization in Taiwan to initiate the development of wafer bumping, TAB and COG process. He has been one of the pioneers in developing Taiwan TFT LCD industry and cofounder of two Taiwanese TFT LCD Companies, E-Ink and HannStar. He serves as founding committee chairman of SEMCON Taiwan electronic packaging. From 2010 to 2014, he is the Senior VP of RD in Unimicron and responsible for the advanced substrate development. In 2014, he founded a system integration company; SiPlus Co. In SiPlus, he has developed 2.0D, 2.2D structure and process of integrated substrate for the heterogeneous integration.

He has many invited speeches in advanced substrate and packaging development all over the world. He has been regarded as the world leading expert in advanced electronic packaging.

Dr. Hu has substantial contributions to Taiwan semiconductor packaging, TFT LCD display and substrate development and manufacture. He has over 100 patents in above fields.